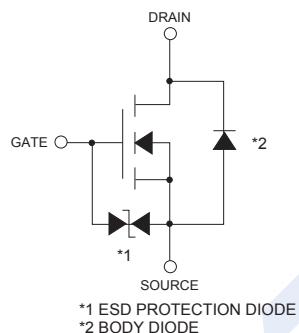
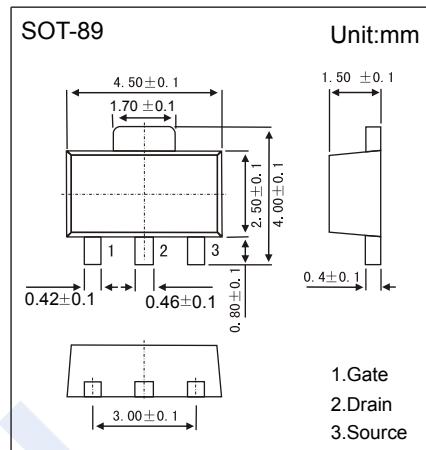


N-Channel MOSFET

RHP020N06 (KHP020N06)

■ Features

- $V_{DS} (V) = 60V$
- $I_D = 2 A (V_{GS} = 10V)$
- $R_{DS(ON)} < 200m\Omega (V_{GS} = 10V)$
- $R_{DS(ON)} < 280m\Omega (V_{GS} = 4.5V)$
- $R_{DS(ON)} < 340m\Omega (V_{GS} = 4V)$
- High speed switching



*1 ESD PROTECTION DIODE
*2 BODY DIODE

■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	± 2	A
Pulsed Drain Current	I_{DM}	± 8	
Power Dissipation	P_D	0.5	W
		2	
Thermal Resistance.Junction- to-Ambient (Note.1)	R_{thJA}	250	$^\circ C/W$
		62.5	
Junction Temperature	T_J	150	$^\circ C$
Storage Temperature Range	T_{stg}	-55 to 150	

Note.1:When mounted on a 40X40X0.7mm ceramic board

N-Channel MOSFET

RHP020N06 (KHP020N06)

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V _{DSS}	I _D =1 mA, V _{GS} =0V	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1	uA
Gate-Body Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±10	uA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =10V , I _D =1mA	1		2.5	V
Static Drain-Source On-Resistance	R _{D(on)}	V _{GS} =10V, I _D =2A			200	m Ω
		V _{GS} =4.5V, I _D =2A			280	
		V _{GS} =4V, I _D =2A			340	
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =2A	2			S
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =10V, f=1MHz		140		pF
Output Capacitance	C _{oss}			50		
Reverse Transfer Capacitance	C _{rss}			40		
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =30V, I _D =2A		7	14	nC
Gate Source Charge	Q _{gs}			1		
Gate Drain Charge	Q _{gd}			2		
Turn-On DelayTime	t _{d(on)}	V _{GS} =10V, V _{DS} =30V, R _L =30Ω, R _{GEN} =10Ω, I _D =1A		7		ns
Turn-On Rise Time	t _r			10		
Turn-Off DelayTime	t _{d(off)}			22		
Turn-Off Fall Time	t _f			18		
Maximum Body-Diode Continuous Current	I _s				2	A
Source current Pluse	I _{SP}				8	
Diode Forward Voltage	V _{SD}	I _s =2A, V _{GS} =0V			1.2	V

Note. The static characteristics in Figures 1 to 6 are obtained using <300us pulses, duty cycle 0.5% max.

■ Marking

Marking	LR
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N-Channel MOSFET

RHP020N06 (KHP020N06)

■ Typical Characteristics

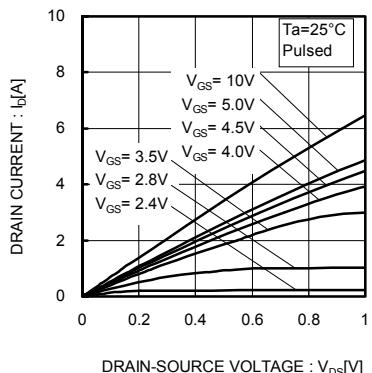


Fig.1 Typical Output Characteristics(I)

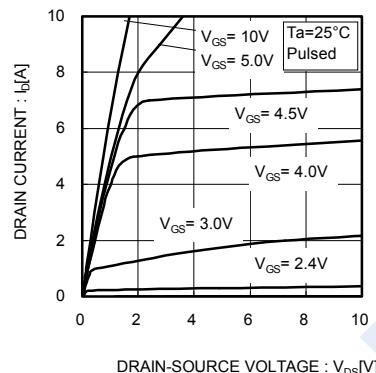


Fig.2 Typical Output Characteristics(II)

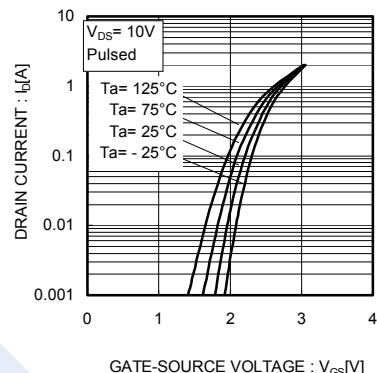


Fig.3 Typical Transfer Characteristics

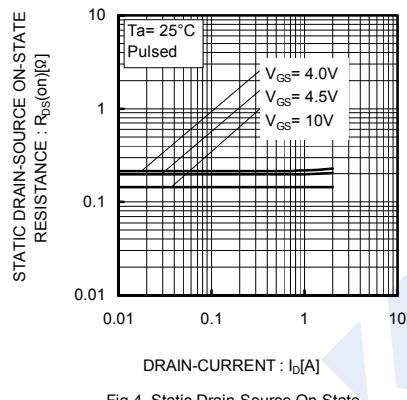


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current(I)

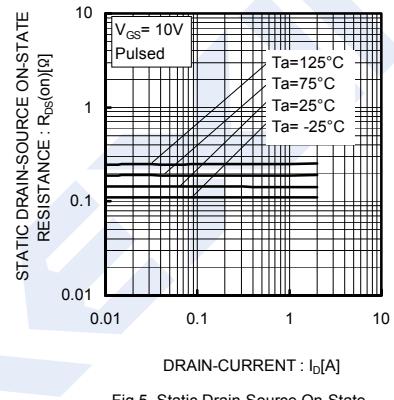


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(II)

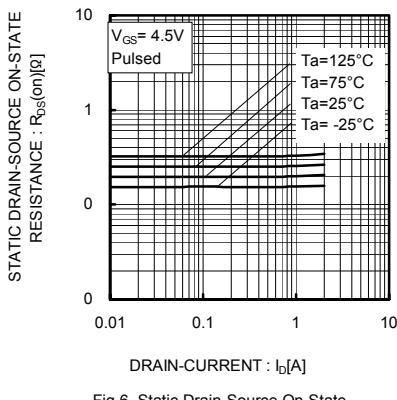


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(III)

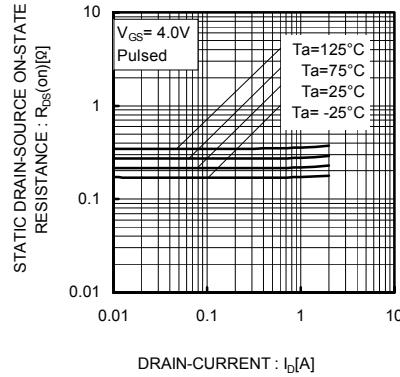


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(IV)

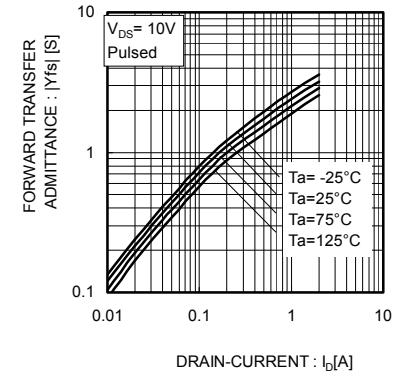


Fig.8 Forward Transfer Admittance vs. Drain Current

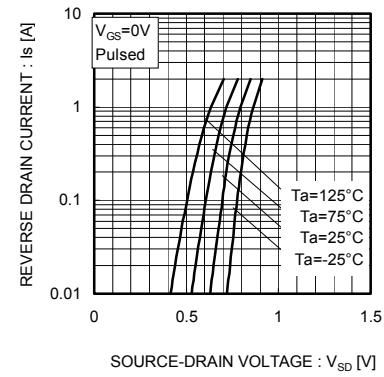


Fig.9 Reverse Drain Current vs. Source-Drain Voltage

N-Channel MOSFET

RHP020N06 (KHP020N06)

■ Typical Characteristics

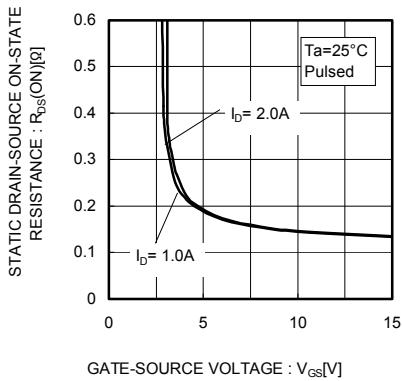


Fig.10 Static Drain-Source On-State
Resistance vs. Gate Source Voltage

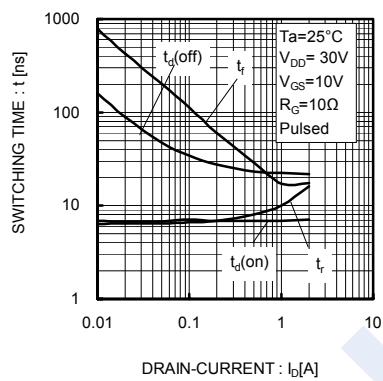


Fig.11 Switching Characteristics

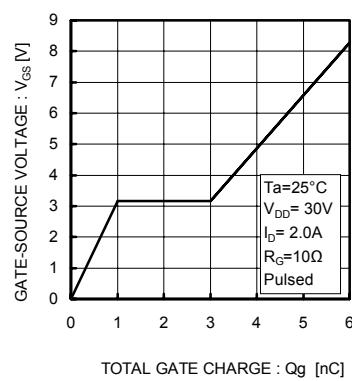


Fig.12 Dynamic Input Characteristics

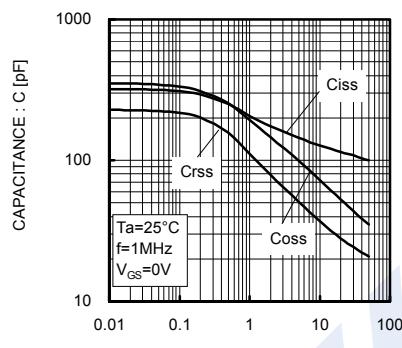


Fig.13 Typical Capacitance
vs. Drain-Source Voltage

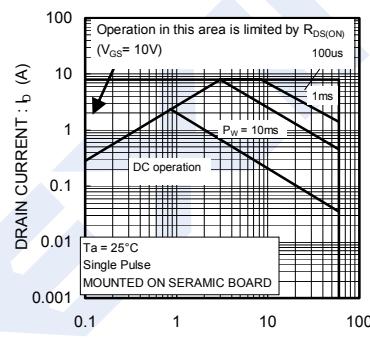


Fig.14 Maximum Safe Operating Aera

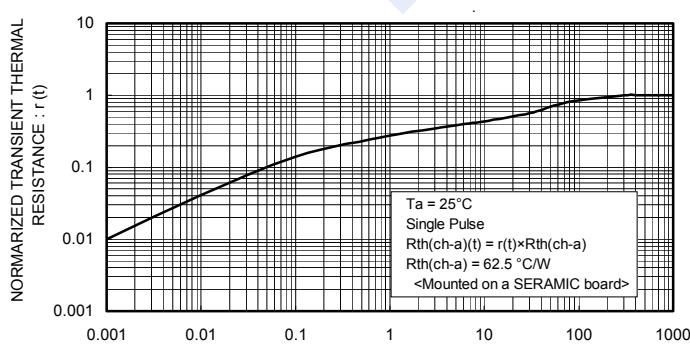


Fig.15 Normalized Transient Thermal Resistance vs. Pulse Width